



**SLOVENSKI STANDARD**  
**oSIST prEN IEC 60146-1-1:2023**  
**01-februar-2023**

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**Polprevodniški pretvorniki - Splošne zahteve in linijsko komutirani pretvorniki - 1-1. del: Specifikacija osnovnih zahtev**

Semiconductor converters - General requirements and line commutated converters - Part 1-1: Specification of basic requirements

Halbleiter-Stromrichter - Allgemeine Anforderungen und netzgeführte Stromrichter - Teil 1-1: Festlegung der Grundanforderungen

Convertisseurs à semiconducteurs - Exigences générales et convertisseurs commutés par le réseau - Partie 1-1: Spécification des exigences de base

**Ta slovenski standard je istoveten z: prEN IEC 60146-1-1:2022**

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**ICS:**

29.045	Polprevodniški materiali	Semiconducting materials
29.200	Usmerniki. Pretvorniki. Stabilizirano električno napajanje	Rectifiers. Convertors. Stabilized power supply

**oSIST prEN IEC 60146-1-1:2023**

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22/361/CDV

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IEC TC 22 : POWER ELECTRONIC SYSTEMS AND EQUIPMENT

SECRETARIAT:

Switzerland

SECRETARY:

Ms Chuanhong Zhao

OF INTEREST TO THE FOLLOWING COMMITTEES:

TC 14, TC 26, TC 27, SC 32B, SC 77A, ACEC

PROPOSED HORIZONTAL STANDARD:

Other TC/SCs are requested to indicate their interest, if any, in this CDV to the secretary.

FUNCTIONS CONCERNED:

 EMC ENVIRONMENT QUALITY ASSURANCE SAFETY SUBMITTED FOR CENELEC PARALLEL VOTING NOT SUBMITTED FOR CENELEC PARALLEL VOTING**Attention IEC-CENELEC parallel voting**

The attention of IEC National Committees, members of CENELEC, is drawn to the fact that this Committee Draft for Vote (CDV) is submitted for parallel voting.

The CENELEC members are invited to vote through the CENELEC online voting system.

This document is still under study and subject to change. It should not be used for reference purposes.

Recipients of this document are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation.

TITLE:

**Semiconductor converters – General requirements and line commutated converters – Part 1-1: Specification of basic requirements**

PROPOSED STABILITY DATE: 2028

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<https://standards.iteh.ai/catalog/standards/sist/dcccb93a-4719-4f0a-bd83-50ec00b8520f/osist-pren-iec-60146-1-1-2023>

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR CONVERTERS –  
GENERAL REQUIREMENTS AND LINE COMMUTATED CONVERTERS –****Part 1-1: Specification of basic requirements**

## FOREWORD

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International Standard IEC 60146-1-1 has been prepared by IEC technical committee 22: Power electronic systems and equipment.

This fifth edition cancels and replaces the fourth edition published in 2009. This fifth edition constitutes a technical revision.

This fifth edition introduces four main changes:

- a) re-edition of the whole standard according to the current directives;
- b) deletion of safety-related descriptions considering coordination with IEC 62477 series;
- c) changes of calculation methods of inductive voltage regulation;
- d) changes considering coordination with IEC 61378 series;

The text of this standard is based on the following documents:

FDIS	Report on voting
to be determined	to be determined

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The main purposes of the IEC 60146-1 series are as follows.

Part 1-1, IEC 60146-1-1, Specification of basic requirements:

- to establish basic terms and definitions;
- to specify service conditions which influence the basis of rating;
- to specify test requirements for electronic power converters and assemblies, standard design, (for special design, see IEC TR 60146-1-2);
- to specify basic performance requirements;
- to give application oriented requirements for semiconductor power converters.

Part 1-2, IEC TR 60146-1-2, Application guideline:

- to give additional information on test conditions and components (for example: semiconductor valve devices), when required for their use in semiconductor power converters, in addition to or as a modification on existing standards;
- to provide useful reference, calculation factors, formulae and diagrams pertaining to power converter practice.

A list of all parts of the IEC 60146 series, under the general title: *Semiconductor converters*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.



# SEMICONDUCTOR CONVERTERS – GENERAL REQUIREMENTS AND LINE COMMUTATED CONVERTERS –

## Part 1-1: Specification of basic requirements

### 1 Scope

This International Standard specifies the requirements for the performance of all semiconductor power converters and semiconductor power switches using controllable and/or non-controllable electronic valve devices.

The electronic valve devices mainly comprise semiconductor devices, either not controllable (i.e. rectifier diodes) or controllable (i.e. thyristors, triacs, turn-off thyristors and power transistors). The controllable devices can be reverse blocking or reverse conducting and controlled by means of current, voltage or light. Non-bistable devices are assumed to be operated in the switched mode.

This standard is primarily intended to specify the basic requirements for converters in general and the requirements applicable to line commutated converters for conversion of AC power to DC power or vice versa. Parts of this standard are also applicable to other types of electronic power converter provided that they do not have their own product standards.

These specific equipment requirements are applicable to semiconductor power converters that either implement power conversion or use commutation (for example semiconductor self-commutated converters) or involve particular applications (for example semiconductor converters for DC motor drives) or include a combination of said characteristics (for example direct DC converters for electric rolling stock).

This standard is applicable to all power converters not covered by a dedicated product standard, or if special features are not covered by the dedicated product standard. Generally dedicated product standards for power converters should refer to this International Standard.

NOTE 1 This standard is not intended to define EMC requirements. It covers all phenomena and therefore introduces references to dedicated standards which are applicable according to their scope.

NOTE 2 For the information on converter transformers, related to this International Standard, see IEC 61378-1.

### 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-151:2001, *International Electrotechnical Vocabulary (IEV) – Part 151: Electrical and magnetic devices*

IEC 60050-551:1998, *International Electrotechnical Vocabulary – Part 551: Power electronics*

IEC 60050-551-20:2001, *International Electrotechnical Vocabulary – Part 551-20: Power electronics – Harmonic analysis*

IEC 60664-1:2007, *Insulation coordination for equipment within low-voltage systems – Part 1: Principles, requirements and tests*

- 42 IEC 61000-2-2:2002, *Electromagnetic compatibility (EMC) – Part 2-2: Environment –*  
 43 *Compatibility levels for low-frequency conducted disturbances and signalling in public low-*  
 44 *voltage power supply systems*
- 45 IEC 61000-2-4:2002, *Electromagnetic compatibility (EMC) – Part 2-4: Environment –*  
 46 *Compatibility levels in industrial plants for low-frequency conducted disturbances*
- 47 IEC 61000-3-2, *Electromagnetic compatibility (EMC) – Part 3-2: Limits – Limits for harmonic*  
 48 *current emissions (equipment with input current  $\leq 16$  A per phase)*
- 49 IEC 61000-3-12:2011, *Electromagnetic compatibility (EMC) – Part 3-12: Limits – Limits for*  
 50 *harmonic currents produced by equipment connected to public low-voltage systems with input*  
 51 *current  $> 16$  A and  $\leq 75$  A per phase*
- 52 IEC 61000-4-7, *Electromagnetic compatibility (EMC) – Part 4-7: Testing and measurement*  
 53 *techniques – General guide on harmonics and interharmonics measurements and*  
 54 *instrumentation, for power supply systems and equipment connected thereto*
- 55 IEC 61000-6-1, *Electromagnetic compatibility (EMC) – Part 6-1: Generic standards –*  
 56 *Immunity for residential, commercial and light-industrial environments*
- 57 IEC 61000-6-2, *Electromagnetic compatibility (EMC) – Part 6-2: Generic standards –*  
 58 *Immunity for industrial environments*
- 59 IEC 61000-6-3, *Electromagnetic compatibility (EMC) – Part 6-3: Generic standards –*  
 60 *Emission standard for residential, commercial and light-industrial environments*
- 61 IEC 61000-6-4, *Electromagnetic compatibility (EMC) – Part 6-4: Generic standards –*  
 62 *Emission standard for industrial environments* 60146-1-1:2023  
<https://standards.iteh.ai/catalog/standards/sist/dcccb93a-4719-4f0a-bd83->
- 63 IEC 62477-1:2012, *Safety requirements for power electronic converter systems and*  
 64 *equipment - Part 1: General*
- 65 IEC 62477-2:2018, *Safety requirements for power electronic converter systems and*  
 66 *equipment - Part 2: Power electronic converters from 1 000 V AC or 1 500 V DC up to 36 kV*  
 67 *AC or 54 kV DC*

### 68 3 Terms and definitions

69 For the purposes of this document, the following terms and definitions apply.

70 ISO and IEC maintain terminology databases for use in standardization at the following  
 71 addresses:

- 72 • ISO Online browsing platform: available at <https://www.iso.org/obp>
- 73 • IEC Electropedia: available at <https://www.electropedia.org>

74 In this standard, IEC definitions are used wherever possible, particularly those in IEC 60050-  
 75 551 and IEC 60050-551-20.

76 All the terms listed in this clause are not necessarily used in this International Standard,  
 77 however they are necessary to establish a common understanding in the application of  
 78 semiconductor converters.

79 The policy adopted is as follows:

- 80 a) when an existing IEV definition needs amplification or additional information, the title, the  
81 reference and the additional text are given;
- 82 b) explanations and figures are given in 4.2;
- 83 c) terms used in connection with converter faults are defined in IEC TR 60146-1-2.

### 84 **3.1 Semiconductor devices and combinations**

#### 85 **3.1.1**

##### 86 **semiconductor device**

87 device, the essential electric characteristics of which are due to the flow of charge carriers  
88 within one or more semiconductor materials

89 [IEV 151-13-63]

#### 90 **3.1.2**

##### 91 **electronic (power) switch**

92 an operative unit for electronic power switching comprising at least one controllable valve  
93 device

94 [IEV 551-13-01]

#### 95 **3.1.3**

##### 96 **semiconductor switch**

97 an electronic power switch with semiconductor valve devices

98 [IEV 551-13-05]

99 Note 1 to entry: Similar terms are used for electronic switches or power controllers with specific electronic valve  
100 devices, for example thyristor controller, transistor switch.

#### 101 **3.1.4**

##### 102 **non-controllable valve device**

##### 103 **rectifier diode**

104 a reverse blocking valve device the current path of which conducts in its conducting direction  
105 without any control signal being applied

106 [IEV 551-14-04]

#### 107 **3.1.5**

##### 108 **thyristor**

109 bi-stable semiconductor device comprising three or more junctions which can be switched  
110 from the off-state to the on-state or vice versa

111 [IEV 521-04-61]

112 Note 1 to entry: Devices having only three layers but having switching characteristics similar to those of four layers  
113 thyristors may also be called thyristors.

114 Note 2 to entry: The term "thyristor" is used as a generic term to cover the whole range of PNP type devices. It  
115 may be used by itself for any member of the thyristor family when such use does not result in ambiguity or  
116 misunderstanding. In particular, the term "thyristor" is widely used for reverse blocking triode thyristor, formerly  
117 called "silicon controlled rectifier".

#### 118 **3.1.6**

##### 119 **reverse blocking triode thyristor**

120 three-terminal thyristor which for negative anode voltage does not switch, but exhibits a  
121 reverse blocking state

122 [IEV 521-04-63]

- 123 **3.1.7**  
124 **reverse conducting triode thyristor**  
125 three-terminal thyristor which for negative anode voltage does not switch and conducts large  
126 currents at voltages comparable in magnitude to the forward on-state voltage
- 127 [IEV 521-04-65]
- 128 **3.1.8**  
129 **bidirectional triode thyristor**  
130 **triac**  
131 three-terminal thyristor having substantially the same switching behaviour in the first and third  
132 quadrants of the current-voltage characteristic
- 133 [IEV 521-04-67, modified]
- 134 **3.1.9**  
135 **turn-off thyristor**  
136 **GTO**  
137 thyristor which can be switched from the on-state to the off-state and vice versa by applying  
138 control signals of appropriate polarity to the gate terminal
- 139 [IEV 521-04-68]
- 140 Note 1 to entry: Also known as gate turn-off thyristor.
- 141 **3.1.10**  
142 **power transistor**  
143 transistor designed for switching from the on-state to the off-state and vice versa by applying  
144 control signals of appropriate polarity to the base or gate terminal
- 145 Note 1 to entry: The structure of the device intrinsically provides the capability of amplification (see IEC 521-04-46)
- 146 Note 2 to entry: Different technologies of power transistors are used such as bipolar transistors, insulated gate  
147 bipolar transistors (IGBT), metal-oxide-semiconductor field-effect transistors, (MOSFET) etc.
- 148 **3.1.11**  
149 **valve device stack**  
150 a single structure of one or more electronic valve devices with its (their) associated  
151 mounting(s) and auxiliaries if any
- 152 [IEV 551-14-12]
- 153 **3.1.12**  
154 **valve device assembly**  
155 an electrically and mechanically combined assembly of electronic valve devices or stacks,  
156 complete with all its connections and auxiliaries in its own mechanical structure
- 157 Note 1 to entry: Similar terms are applied to stacks or assemblies comprising specific electronic valve devices, for  
158 example diode stack (rectifier diodes only), thyristor assembly (thyristors only or in combination with rectifier  
159 diodes).
- 160 [IEV 551-14-13]
- 161 **3.1.13**  
162 **electronic valve device**  
163 an indivisible electronic device for electronic power conversion or electronic power switching,  
164 comprising a non-controllable or bistably controlled unidirectionally conducting current path
- 165 [IEV 551-14-02]

166 **3.1.14**  
167 **semiconductor valve device**  
168 an electronic valve device which is a semiconductor device

169 [IEV 551-14-09]

170 Note 1 to entry: Typical semiconductor valve devices are thyristors, rectifier diodes, bipolar transistors, metal-  
171 oxide-semiconductor field-effect transistors (MOSFET) and insulated-gate bipolar transistors (IGBT).

172 Note 2 to entry: Two or more semiconductor valve devices may be integrated on a common semiconductor chip  
173 (examples: a thyristor and a rectifier diode in a reverse conducting thyristor, a power switching field effect  
174 transistor with its reverse diode) or packaged in a common case (semiconductor power module). These  
175 combinations are considered as separate semiconductor valve devices.

176 **3.1.15**  
177 **(electronic) (power) conversion**  
178 change of one or more of the characteristics of an electric power system essentially without  
179 appreciable loss of power by means of electronic valve devices

180 [IEV 551-11-02]

181 Note 1 to entry: Characteristics include, for example, voltage amplitude, number of phases and frequency,  
182 including zero frequency.

183 **3.1.16**  
184 **(electronic) (power) converter**  
185 an operative unit for electronic power conversion, comprising one or more electronic valve  
186 devices, and auxiliaries if any

187 [IEV 551-12-01, modified]

188 Note 1 to entry: Converter transformers and filters related to network interfacing in terms of electrical  
189 characteristics are excluded from the converter itself. Such devices are part of the system aspect. Any device  
190 necessary to the correct operation of the converter itself are included in the converter, for example filters for  
191 limitation of the  $du/dt$  applied to the valve devices, surge arrestors, etc. Any auxiliary necessary to the correct  
192 operation of the converter itself are included in the converter, for example fans or cooling system.

193 **3.1.17**  
194 **trigger equipment**  
195 **gating equipment**  
196 equipment which provides suitable trigger pulses from a control signal for controllable valve  
197 devices in a converter or power switch including timing or phase shifting circuits, pulse  
198 generating circuits and usually power supply circuits

199 **3.1.18**  
200 **system control equipment**  
201 equipment associated with a power conversion equipment or system which performs  
202 automatic adjustment of the converter output characteristics as a function of a controlled  
203 quantity (for example motor speed, traction force, etc.)

204 **3.1.19**  
205 **semiconductor converter**  
206 an electronic power converter with semiconductor valve devices

207 [IEV 551-12-42]

208 Note 1 to entry: Similar terms for converters in general or for specific kinds of converters or for converters with  
209 other or specific valve devices, for example thyristor converter, transistor inverter.

210 **3.1.20**  
211 **power conversion equipment**  
212 **PCE**  
213 equipment including the electronic power converter and auxiliaries necessary for operation of  
214 the converter itself, or even other parts dedicated to the application and where these parts  
215 cannot be physically separated without preventing the operation of the converter

216 **3.1.21**  
217 **power conversion system**  
218 system consisting of a power conversion equipment and associated components for the  
219 application for example switchgear, reactors or transformers, dedicated filters, etc.

## 220 **3.2 Arms and connections**

221 **3.2.1**  
222 **(valve) arm**  
223 a part of the circuit of an electronic power converter or switch bounded by any two AC or DC  
224 terminals and including one or more simultaneously conducting electronic valve devices  
225 connected together and other components if any

226 [IEV 551-15-01]

227 **3.2.2**  
228 **principal arm**  
229 a valve arm involved in the major transfer of power from one side of the converter or  
230 electronic switch to the other

231 [IEV 551-15-02]

232 **3.2.3**  
233 **auxiliary arm**  
234 any valve arm other than a principal arm

235 Note 1 to entry: Sometimes an auxiliary arm temporarily fulfils more than one of the following functions: by-pass  
236 arm, free-wheeling arm, turn-off arm or regenerative arm.

237 [IEV 551-15-05]

238 **3.2.4**  
239 **by-pass arm**  
240 an auxiliary arm providing a conductive path which allows the current to circulate without an  
241 interchange of power between source and load

242 [IEV 551-15-06]

243 **3.2.5**  
244 **free-wheeling arm**  
245 a by-pass arm containing only non-controllable valve devices

246 [IEV 551-15-07]

247 **3.2.6**  
248 **turn-off arm**  
249 an auxiliary arm which temporarily takes over the current directly from a conducting valve arm,  
250 consisting of one or more latching valve devices which cannot be turned off by a control  
251 signal

252 [IEV 551-15-08]

- 253 **3.2.7**  
254 **regenerative arm**  
255 a valve arm which transfers a part of the power from the load side to the source side
- 256 [IEV 551-15-09]
- 257 **3.2.8**  
258 **converter connection**  
259 the electrical arrangement of valve arms and other components essential for the function of  
260 the main power circuit of a converter
- 261 [IEV 551-15-10]
- 262 Note 1 to entry: Common practice also uses the term “topology” of the converter with the same sense.
- 263 **3.2.9**  
264 **basic converter connection**  
265 the electrical arrangement of principal arms in a converter
- 266 [IEV 551-15-11]
- 267 **3.2.10**  
268 **single-way connection (of a converter)**  
269 a converter connection such that the current through each of the phase terminals of the AC  
270 circuit is unidirectional
- 271 [IEV 551-15-12]
- 272 **3.2.11**  
273 **double-way connection (of a converter)**  
274 a converter connection such that the current through each of the phase terminals of the AC  
275 circuit is bidirectional
- 276 [IEV 551-15-13]
- 277 **3.2.12**  
278 **bridge connection**  
279 a double-way connection of pairs of arms such that the centre terminals are the phase  
280 terminals of the AC circuit, and that the outer terminals of like polarity are connected together  
281 and are the DC terminals
- 282 [IEV 551-15-14]
- 283 **3.2.13**  
284 **uniform connection**  
285 a connection with either all principal arms controllable or all principal arms non-controllable
- 286 [IEV 551-15-15]
- 287 **3.2.14**  
288 **non-uniform connection**  
289 a connection with both controllable and non-controllable principal arms
- 290 [IEV 551-15-18]
- 291 **3.2.15**  
292 **series connection**  
293 connection of two-terminal networks so that they form a single path